

Mechanical standardization of semiconductor devices —

**Part 4: Recommendations for a coding
system and classification into forms of
package outlines for semiconductor
devices**

Committees responsible for this British Standard

The preparation of this British Standard was entrusted by the Electronic Components Standards Policy Committee (ECL/-) to Technical Committee ECL/24, upon which the following bodies were represented:

- EEA (the Association of Electronics, Telecommunications and Business Equipment Industries)
- Electronic Components Industry Federation
- GAMBICA (BEAMA Ltd.)
- Ministry of Defence
- National Supervising Inspectorate
- Society of British Aerospace Companies Limited

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Contents

	Page
Committees responsible	Inside front cover
National foreword	ii
1 Scope	1
2 Coding system of package outlines for semiconductor devices	1
3 Classification into forms of package outlines for semiconductor devices	1
Appendix A Classification into forms of package outline drawings for semiconductor devices	2